

ABSTRACT

The purpose of this invention is to provide a magnetron sputtering apparatus capable of attaching masks on disk substrates and capable of conducting sputtering while disk substrates are being rotated on the central axis without complicated mechanisms or complicated processes.

For this purpose, in the sputtering apparatus of this invention, a magnetic field generating means is provided above the sputtering chamber so as to apply magnetic field in the sputtering chamber 11 providing discharge space. A target 21 is arranged at the upper portion of this sputtering chamber 11 so that the magnetic field by said magnetic field generating means is applied. A disk transport chamber is provided which is connected to said sputtering chamber 11 through the opening 32 formed on the bottom wall 30. In this disk transport chamber 12, a disk pusher 34 is provided which places thereon the disk substrate 31 for depositing sputter film, transports to the opening 32 of said sputtering chamber 11 and rotates said disk substrate 31 on the plane of said disk pusher. In the sputtering chamber 11, a rotation center mask 27 is provided which makes contact with the upper center portion of said disk substrate 31 placed on said disk pusher 34, and rotates with the rotation of said disk substrate 31.

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